



PCB Number:	PMP10653
PCB Rev:	E1

1

PCB LOGO Texas Instruments PCB LOGO Pb-Free Symbol You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

4

5

6

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).

Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

3

Label Table		
Variant	Label Text	
001	ChangeMe!	
002	ChangeMe!	

2

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

1

С

D

ZZ2 Assembly Note These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3 Assembly Note These assemblies must be clean and free from flux and all contaminants. Use of no

ZZ4 Assembly Note These assemblies must comply with workmanship standards IPC-A-610 Class 2, un

			c
of no clean flux is not acceptable.			
2, unless otherwise specified.			
			D
		Designed for: Public Rele	ease Mod. Date: 8/28/2015
Texas Instruments and/or its licensors do not warrant the accuracy or completeness warrant that this design will meet the specifications, will be suitable for your applicati licensors do not warrant that the design is production worthy. You should completely	of this specification or any information contained therein. Texas Instruments and/or its on or fit for any particular purpose, or will operate in an implementation. Texas Instrume validate and test your design implementation to confirm the system functionality for yo	Project Title: Automotive Number: PMP10653 Rev: E1 Sheet Title: s licensors do not SVN Rev: Not in version control Assembly Variant:001 ents and/or its Drawn By: File: PMP10653_Hardwa	Camera Module Sheet: 1 of 1 re.SchDoc Size: B http://www.ti.com
2 3		5	6

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